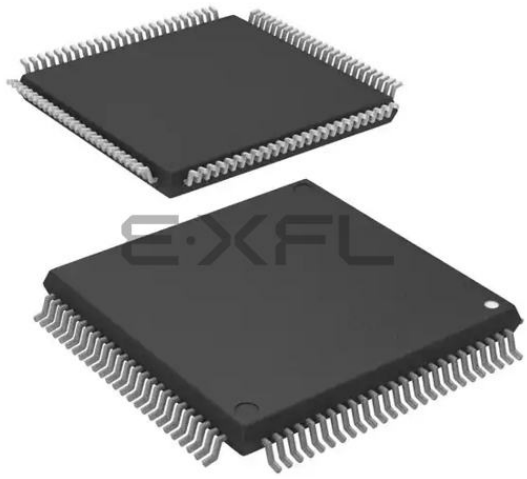
Renesas Electronics America Inc - UPD78F1166AGF-GAS-AX Datasheet



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Details	
Product Status	Active
Core Processor	78K/0R
Core Size	16-Bit
Speed	20MHz
Connectivity	3-Wire SIO, I²C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	83
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 16x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/upd78f1166agf-gas-ax

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Table 3-6. Extended SFR (2nd SFR) List (2/5)

Address	Special Function Register (SFR) Name	Symbol		R/W	Manipulable Bit Range			After Reset
					1-bit	8-bit	16-bit	
F0110H	Serial mode register 00	SMR00		R/W	–	–	√	0020H
F0111H								
F0112H	Serial mode register 01	SMR01		R/W	–	–	√	0020H
F0113H								
F0114H	Serial mode register 02	SMR02		R/W	–	–	√	0020H
F0115H								
F0116H	Serial mode register 03	SMR03		R/W	–	–	√	0020H
F0117H								
F0118H	Serial communication operation setting register 00	SCR00		R/W	–	–	√	0087H
F0119H								
F011AH	Serial communication operation setting register 01	SCR01		R/W	–	–	√	0087H
F011BH								
F011CH	Serial communication operation setting register 02	SCR02		R/W	–	–	√	0087H
F011DH								
F011EH	Serial communication operation setting register 03	SCR03		R/W	–	–	√	0087H
F011FH								
F0120H	Serial channel enable status register 0	SE0L	SE0	R	√	√	√	0000H
F0121H		–			–	–		
F0122H	Serial channel start register 0	SS0L	SS0	R/W	√	√	√	0000H
F0123H		–			–	–		
F0124H	Serial channel stop register 0	ST0L	ST0	R/W	√	√	√	0000H
F0125H		–			–	–		
F0126H	Serial clock select register 0	SPS0L	SPS0	R/W	–	√	√	0000H
F0127H		–			–	–		
F0128H	Serial output register 0	SO0		R/W	–	–	√	0F0FH
F0129H								
F012AH	Serial output enable register 0	SOE0L	SOE0	R/W	√	√	√	0000H
F012BH		–			–	–		
F0134H	Serial output level register 0	SOL0L	SOL0	R/W	–	√	√	0000H
F0135H		–			–	–		
F0140H	Serial status register 10	SSR10L	SSR10	R	–	√	√	0000H
F0141H		–			–	–		
F0142H	Serial status register 11	SSR11L	SSR11	R	–	√	√	0000H
F0143H		–			–	–		
F0144H	Serial status register 12	SSR12L	SSR12	R	–	√	√	0000H
F0145H		–			–	–		
F0146H	Serial status register 13	SSR13L	SSR13	R	–	√	√	0000H
F0147H		–			–	–		
F0148H	Serial flag clear trigger register 10	SIR10L	SIR10	R/W	–	√	√	0000H
F0149H		–			–	–		
F014AH	Serial flag clear trigger register 11	SIR11L	SIR11	R/W	–	√	√	0000H
F014BH		–			–	–		

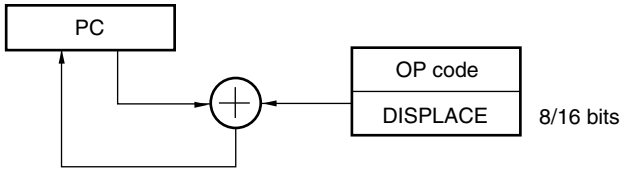
3.3 Instruction Address Addressing

3.3.1 Relative addressing

[Function]

Relative addressing stores in the program counter (PC) the result of adding a displacement value included in the instruction word (signed complement data: −128 to +127 or −32768 to +32767) to the program counter (PC)'s value (the start address of the next instruction), and specifies the program address to be used as the branch destination. Relative addressing is applied only to branch instructions.

Figure 3-22. Outline of Relative Addressing



3.3.2 Immediate addressing

[Function]

Immediate addressing stores immediate data of the instruction word in the program counter, and specifies the program address to be used as the branch destination.

For immediate addressing, CALL !!addr20 or BR !!addr20 is used to specify 20-bit addresses and CALL !addr16 or BR !addr16 is used to specify 16-bit addresses. 0000 is set to the higher 4 bits when specifying 16-bit addresses.

Figure 3-23. Example of CALL !!addr20/BR !!addr20

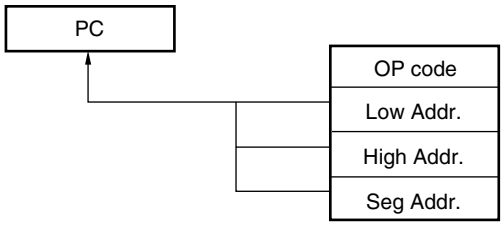


Figure 3-24. Example of CALL !addr16/BR !addr16

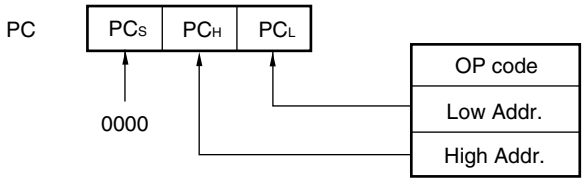
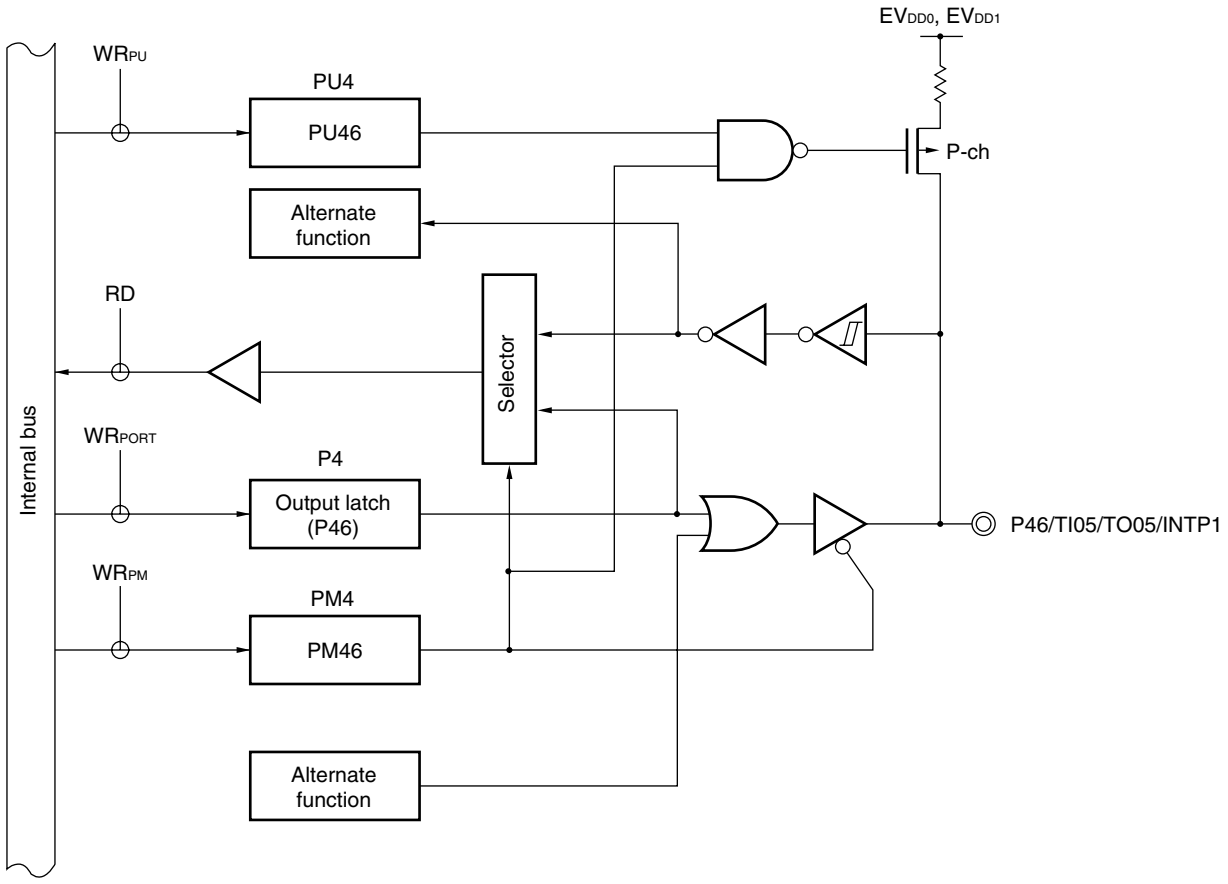


Table 4-2. Port Functions (2/2)

Function Name	I/O	Function	After Reset	Alternate Function
P60	I/O	Port 6. 8-bit I/O port. Output of P60 to P63 can be set to N-ch open-drain output (6 V tolerance). Input/output can be specified in 1-bit units. For only P64 to P67, use of an on-chip pull-up resistor can be specified by a software setting.	Input port	SCL0
P61				SDA0
P62				–
P63				–
P64				$\overline{RD}$
P65				$\overline{WR0}$
P66				$\overline{WR1}$
P67				ASTB
P70 to P73	I/O	Port 7. 8-bit I/O port. Input/output can be specified in 1-bit units. Use of an on-chip pull-up resistor can be specified by a software setting.	Input port	KR0/EX16 to KR3/ EX19
P74 to P77				KR4/EX20/INTP8 to KR7/EX23/INTP11
P80 to P87	I/O	Port 8. 8-bit I/O port. Input/output can be specified in 1-bit units. Use of an on-chip pull-up resistor can be specified by a software setting.	Input port	EX0 to EX7
P110	I/O	Port 11. 2-bit I/O port. Input/output can be specified in 1-bit units.	Input port	ANO0
P111				ANO1
P120	I/O	Port 12. 1-bit I/O port and 4-bit input port. For only P120, use of an on-chip pull-up resistor can be specified by a software setting.	Input port	INTP0/EXLVI
P121	Input			X1
P122				X2/EXCLK
P123				XT1
P124				XT2
P130	Output	Port 13. 1-bit output port and 1-bit I/O port. For only P131, use of an on-chip pull-up resistor can be specified by a software setting.	Output port	–
P131	I/O		Input port	TI06/TO06
P140	I/O	Port 14. 6-bit I/O port. Input of P142 and P143 can be set to TTL input buffer. Output of P142 to P144 can be set to the N-ch open-drain output (V_{DD} tolerance). Input/output can be specified in 1-bit units. Use of an on-chip pull-up resistor can be specified by a software setting.	Input port	PCLBUZ0/INTP6
P141				PCLBUZ1/INTP7
P142				$\overline{SCK20}$/SCL20
P143				SI20/RxD2/SDA20
P144				SO20/TxD2
P145				TI07/TO07
P150 to P157	I/O	Port 15. 8-bit I/O port. Input/output can be specified in 1-bit units.	Digital input port	ANI8 to ANI15

Figure 4-21. Block Diagram of P46



P4: Port register 4
PU4: Pull-up resistor option register 4
PM4: Port mode register 4
RD: Read signal
WR××: Write signal

(2) Setting procedure when using I/O pins of simplified IIC10 and IIC20 functions

<1> After reset release, the port mode is the input mode (Hi-Z).

<2> Externally pull up the pin to be used (on-chip pull-up resistor cannot be used).

In case of simplified IIC10: P03, P04
In case of simplified IIC20: P142, P143

<3> Set the output latch of the corresponding port to 1.

<4> Set the corresponding bit of the POMn register to 1 to set the N-ch open drain output (V_{DD} withstand voltage) mode.

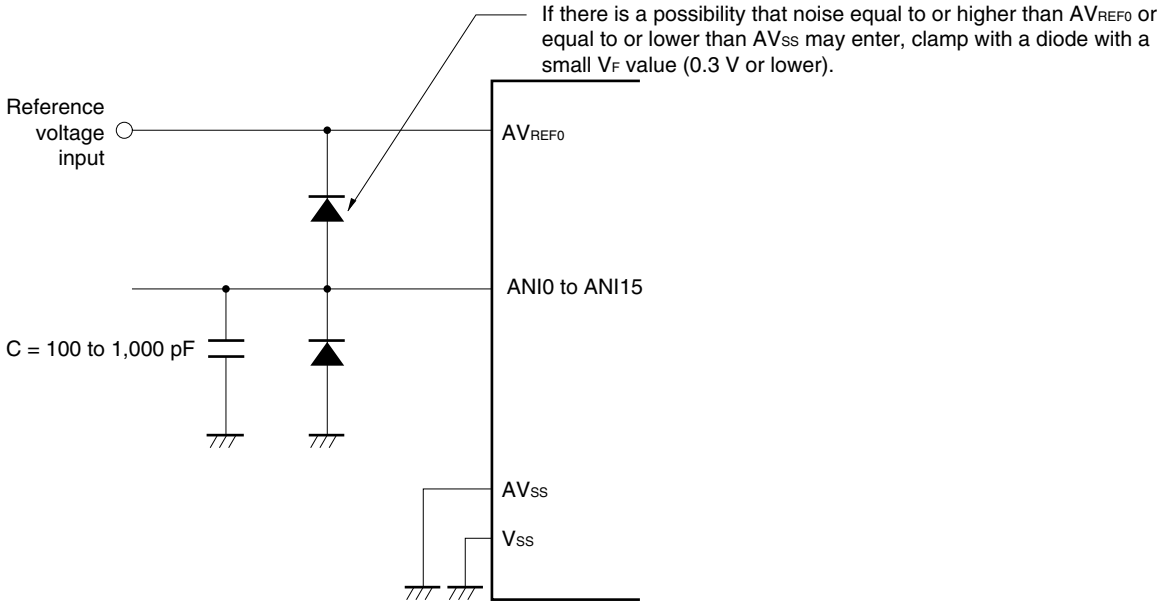
<5> Set the corresponding bit of the PMn register to the output mode (data I/O is possible in the output mode).

At this time, the output data is high level, so the pin is in the Hi-Z state.

<6> Enable the operation of the serial array unit and set the mode to the simplified IIC mode.

Remark n = 0, 14

Figure 11-26. Analog Input Pin Connection



(6) ANI0/P20 to ANI7/P27 and ANI8/P150 to ANI15/P157

<1> The analog input pins (ANI0 to ANI7) are also used as input port pins (P20 to P27).
The analog input pins (ANI8 to ANI15) are also used as input port pins (P150 to P157).
When A/D conversion is performed with any of ANI0 to ANI15 selected, do not access P20 to P27 and P150 to P157 while conversion is in progress; otherwise the conversion resolution may be degraded. It is recommended to select pins used as P20 to P27 and P150 to P157 starting with the ANI0/P20 that is the furthest from AV_{REF0}.

<2> If a digital pulse is applied to the pins adjacent to the pins currently used for A/D conversion, the expected value of the A/D conversion may not be obtained due to coupling noise. Therefore, do not apply a pulse to the pins adjacent to the pin undergoing A/D conversion.

(7) Input impedance of ANI0 to ANI15 pins

This A/D converter charges a sampling capacitor for sampling during sampling time.
Therefore, only a leakage current flows when sampling is not in progress, and a current that charges the capacitor flows during sampling. Consequently, the input impedance fluctuates depending on whether sampling is in progress, and on the other states.
To make sure that sampling is effective, however, it is recommended to keep the output impedance of the analog input source to within 10 kΩ, and to connect a capacitor of about 100 pF to the ANI0 to ANI15 pins (see **Figure 11-26**).

(8) AV_{REF0} pin input impedance

A series resistor string of several tens of kΩ is connected between the AV_{REF0} and AV_{SS} pins.
Therefore, if the output impedance of the reference voltage source is high, this will result in a series connection to the series resistor string between the AV_{REF0} and AV_{SS} pins, resulting in a large reference voltage error.

(11) Serial output enable register m (SOEm)

SOEm is a register that is used to enable or stop output of the serial communication operation of each channel.

Channel n that enables serial output cannot rewrite by software the value of SOmn of the serial output register m (SOm) to be described below, and a value reflected by a communication operation is output from the serial data output pin.

For channel n, whose serial output is stopped, the SOmn value of the SOm register can be set by software, and that value can be output from the serial data output pin. In this way, any waveform of the start condition and stop condition can be created by software.

SOEm can be set by a 16-bit memory manipulation instruction.

The lower 8 bits of SOEm can be set with an 1-bit or 8-bit memory manipulation instruction with SOEmL.

Reset signal generation clears this register to 0000H.

Figure 13-14. Format of Serial Output Enable Register m (SOEm)

Address: F012AH, F012BH After reset: 0000H R/W

Symbol	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SOE0	0	0	0	0	0	0	0	0	0	0	0	0	0	SOE02	SOE01	SOE00

Address: F016AH, F016BH After reset: 0000H R/W

Symbol	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SOE1	0	0	0	0	0	0	0	0	0	0	0	0	0	SOE12	0	SOE10

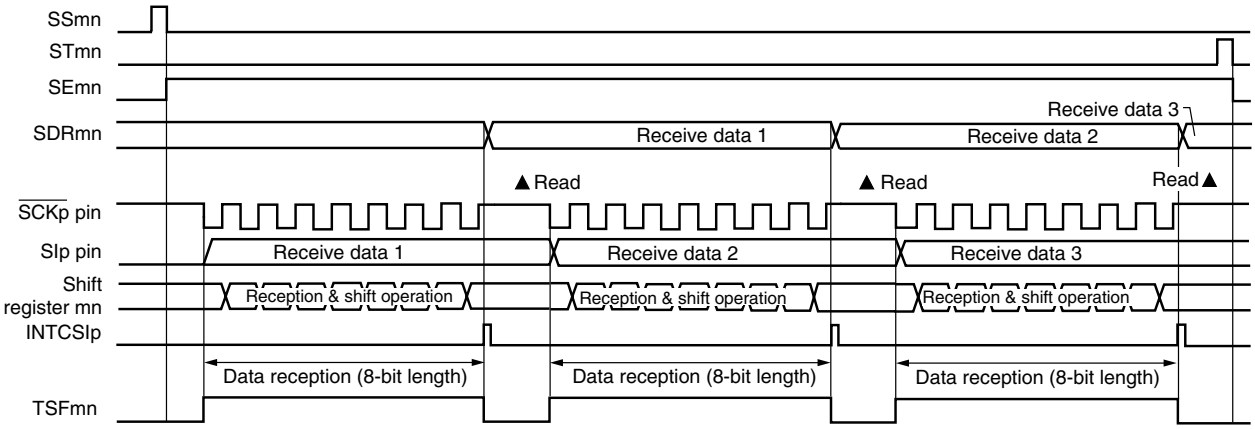
SOEmn	Serial output enable/disable of channel n
0	Stops output by serial communication operation.
1	Enables output by serial communication operation.

Caution Be sure to clear bits 15 to 3 of SOE0, and bits 15 to 3 and 1 of SOE1 to "0".

Remark m: Unit number (m = 0, 1), n: Channel number (n = 0 to 2),
mn = 00 to 02, 10, 12

(3) Processing flow (in single-reception mode)

Figure 13-60. Timing Chart of Slave Reception (in Single-Reception Mode) (Type 1: DAPmn = 0, CKPmn = 0)



Remark m: Unit number (m = 0, 1), n: Channel number (n = 0 to 2), p: CSI number (p = 00, 01, 10, 20)

(1) Register setting

Figure 13-79. Example of Contents of Registers for UART Reception of UART (UART0, UART1, UART2, UART3) (1/2)

(a) Serial output register m (SOm) …The register that not used in this mode.

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SOm						CKOm2	CKOm1	CKOm0						SOm2	SOm1	SOm0
	0	0	0	0	1	×	×	×	0	0	0	0	1	×	×	×

<R> **(b) Serial output enable register m (SOEm) …The register that not used in this mode.**

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SOEm														SOEm2	SOEm1	SOEm0
	0	0	0	0	0	0	0	0	0	0	0	0	0	×	×	×

(c) Serial channel start register m (SSm) … Sets only the bits of the target channel to 1.

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SSm													SSm3	SSm2	SSm1	SSm0
	0	0	0	0	0	0	0	0	0	0	0	0	0/1	×	0/1	×

(d) Serial mode register mn (SMRmn)

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SMRmn	CKSmn	CCSmn						STSmn		SISmn0				MDmn2	MDmn1	MDmn0
	0/1	0	0	0	0	0	0	1	0	0/1	1	0	0	0	1	0

0: Forward (normal) reception
1: Reverse reception

Interrupt sources of channel n
0: Transfer end interrupt

(e) Serial mode register mr (SMRmr)

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SMRmr	CKSmr	CCSmr						STSmr		SISmr0				MDmr2	MDmr1	MDmr0
	0/1	0	0	0	0	0	0	0	0	0	1	0	0	0	1	0/1

Same setting value as CKSmn

Interrupt sources of channel r
0: Transfer end interrupt
1: Buffer empty interrupt

(f) Serial communication operation setting register mn (SCRmn)

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SCRmn	TXEmn	RXEmn	DAPmn	CKPmn		EOCmn	PTCmn1	PTCmn0	DIRmn		SLCmn1	SLCmn0		DLSmn2	DLSmn1	DLSmn0
	0	1	0	0	0	1	0/1	0/1	0/1	0	0	1	0	1	0/1	0/1

Caution For the UART reception, be sure to set SMRmr of channel r that is to be paired with channel n.

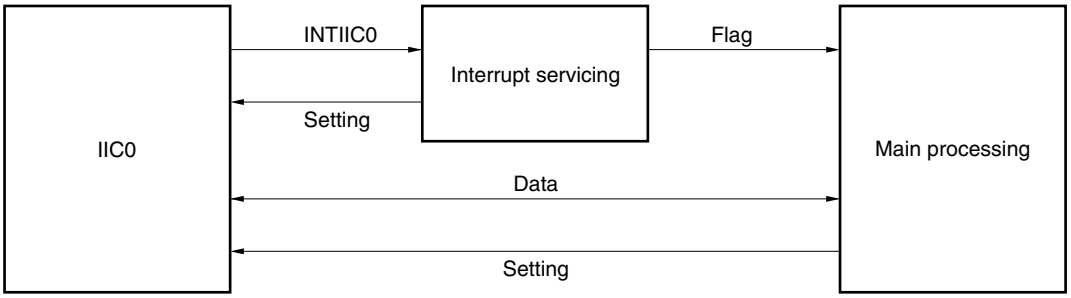
Remark m: Unit number (m = 0, 1), n: Channel number (n = 1, 3), r: Channel number (r = n − 1),
q: UART number (q = 0 to 3)
☐ : Setting is fixed in the UART reception mode, ▒ : Setting disabled (set to the initial value)
×: Bit that cannot be used in this mode (set to the initial value when not used in any mode)
0/1: Set to 0 or 1 depending on the usage of the user

(3) Slave operation

The processing procedure of the slave operation is as follows.

Basically, the slave operation is event-driven. Therefore, processing by the INTIIC0 interrupt (processing that must substantially change the operation status such as detection of a stop condition during communication) is necessary.

In the following explanation, it is assumed that the extension code is not supported for data communication. It is also assumed that the INTIIC0 interrupt servicing only performs status transition processing, and that actual data communication is performed by the main processing.



Therefore, data communication processing is performed by preparing the following three flags and passing them to the main processing instead of INTIIC0.

<1> Communication mode flag

This flag indicates the following two communication statuses.

- Clear mode: Status in which data communication is not performed
- Communication mode: Status in which data communication is performed (from valid address detection to stop condition detection, no detection of ACK from master, address mismatch)

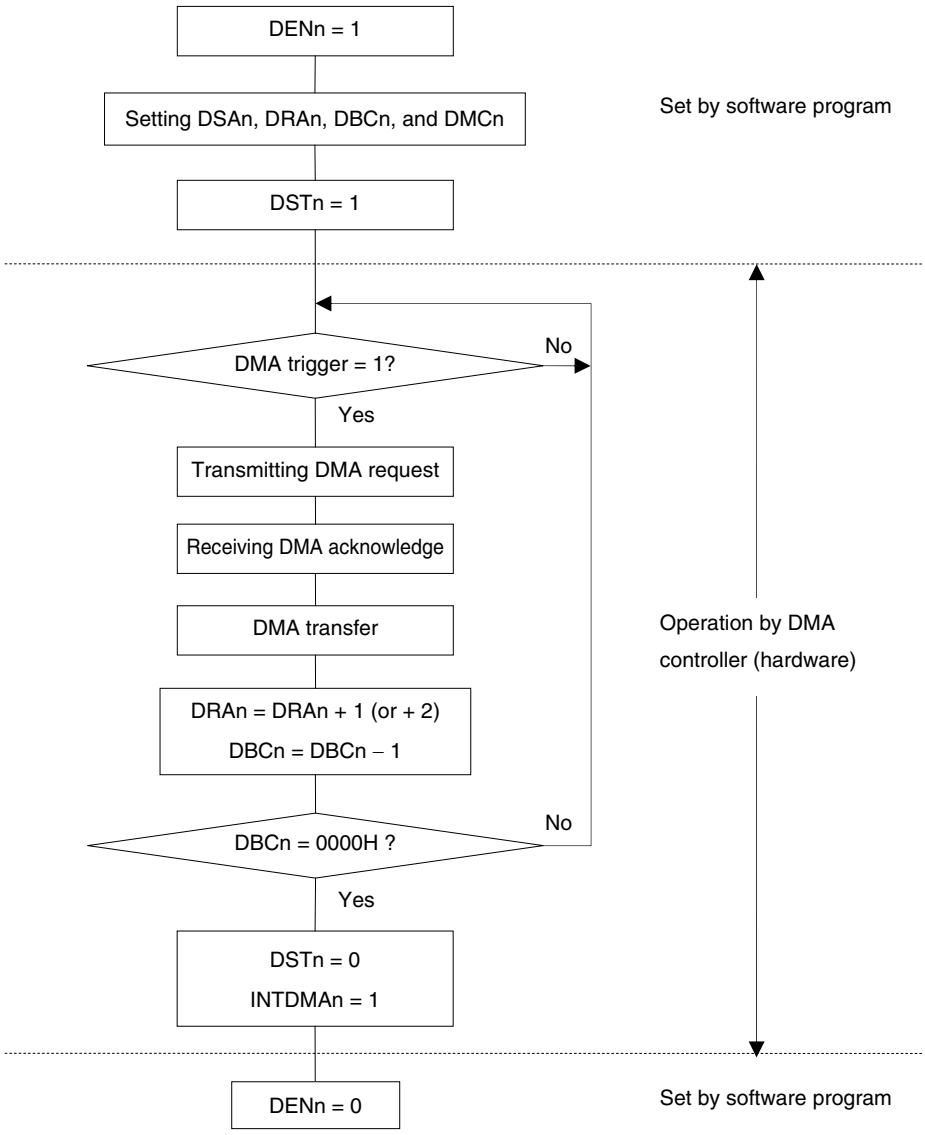
<2> Ready flag

This flag indicates that data communication is enabled. Its function is the same as the INTIIC0 interrupt for ordinary data communication. This flag is set by interrupt servicing and cleared by the main processing. Clear this flag by interrupt servicing when communication is started. However, the ready flag is not set by interrupt servicing when the first data is transmitted. Therefore, the first data is transmitted without the flag being cleared (an address match is interpreted as a request for the next data).

<3> Communication direction flag

This flag indicates the direction of communication. Its value is the same as TRC0.

Figure 16-6. Operation Procedure



Remark n: DMA channel number (n = 0, 1)

17.4.3 Multiple interrupt servicing

Multiple interrupt servicing occurs when another interrupt request is acknowledged during execution of an interrupt.

Multiple interrupt servicing does not occur unless the interrupt request acknowledgment enabled state is selected (IE = 1). When an interrupt request is acknowledged, interrupt request acknowledgment becomes disabled (IE = 0). Therefore, to enable multiple interrupt servicing, it is necessary to set (1) the IE flag with the EI instruction during interrupt servicing to enable interrupt acknowledgment.

Moreover, even if interrupts are enabled, multiple interrupt servicing may not be enabled, this being subject to interrupt priority control. Two types of priority control are available: default priority control and programmable priority control. Programmable priority control is used for multiple interrupt servicing.

In the interrupt enabled state, if an interrupt request with a priority equal to or higher than that of the interrupt currently being serviced is generated, it is acknowledged for multiple interrupt servicing. If an interrupt with a priority lower than that of the interrupt currently being serviced is generated during interrupt servicing, it is not acknowledged for multiple interrupt servicing. Interrupt requests that are not enabled because interrupts are in the interrupt disabled state or because they have a lower priority are held pending. When servicing of the current interrupt ends, the pending interrupt request is acknowledged following execution of at least one main processing instruction execution.

Table 17-5 shows relationship between interrupt requests enabled for multiple interrupt servicing and Figure 17-10 shows multiple interrupt servicing examples.

Table 17-5. Relationship Between Interrupt Requests Enabled for Multiple Interrupt Servicing During Interrupt Servicing

Multiple Interrupt Request / Interrupt Being Serviced		Maskable Interrupt Request								Software Interrupt Request
		Priority Level 0 (PR = 00)		Priority Level 1 (PR = 01)		Priority Level 2 (PR = 10)		Priority Level 3 (PR = 11)		
		IE = 1	IE = 0	IE = 1	IE = 0	IE = 1	IE = 0	IE = 1	IE = 0	
Maskable interrupt	ISP1 = 0 ISP0 = 0	○	×	×	×	×	×	×	×	○
	ISP1 = 0 ISP0 = 1	○	×	○	×	×	×	×	×	○
	ISP1 = 1 ISP0 = 0	○	×	○	×	○	×	×	×	○
	ISP1 = 1 ISP0 = 1	○	×	○	×	○	×	○	×	○
Software interrupt		○	×	○	×	○	×	○	×	○

Remarks 1. ○: Multiple interrupt servicing enabled

2. ×: Multiple interrupt servicing disabled

3. ISP0, ISP1, and IE are flags contained in the PSW.

ISP1 = 0, ISP0 = 0: An interrupt of level 1 or level 0 is being serviced.

ISP1 = 0, ISP0 = 1: An interrupt of level 2 is being serviced.

ISP1 = 1, ISP0 = 0: An interrupt of level 3 is being serviced.

ISP1 = 1, ISP0 = 1: Wait for An interrupt acknowledgment.

IE = 0: Interrupt request acknowledgment is disabled.

IE = 1: Interrupt request acknowledgment is enabled.

4. PR is a flag contained in PR00L, PR00H, PR01L, PR01H, PR02L, PR02H, PR10L, PR10H, PR11L, PR11H, PR12L, and PR12H.

PR = 00: Specify level 0 with ××PR1× = 0, ××PR0× = 0 (higher priority level)

PR = 01: Specify level 1 with ××PR1× = 0, ××PR0× = 1

PR = 10: Specify level 2 with ××PR1× = 1, ××PR0× = 0

PR = 11: Specify level 3 with ××PR1× = 1, ××PR0× = 1 (lower priority level)

(b) When LVI default start function enabled is set (option byte: LVIOFF = 0)

- When starting operation

<1> Start in the following initial setting state.

- Set bit 7 (LVION) of LVIM to 1 (enables LVI operation)
- Clear bit 2 (LVISEL) of the low-voltage detection register (LVIM) to 0 (detects level of supply voltage (V_{DD}))
- Set the low-voltage detection level selection register (LVIS) to 0EH (default value: V_{LVI} = 2.07 V ±0.1 V).
- Set bit 1 (LVIMD) of LVIM to 1 (generates reset when the level is detected)
- Set bit 0 (LVIF) of LVIM to 0 (Detects falling edge "Supply voltage (V_{DD}) ≥ detection voltage (V_{LVI})")

<2> Clear bit 1 (LVIMD) of LVIM to 0 (generates interrupt signal when the level is detected) (default value).

<3> Release the interrupt mask flag of LVI (LVIMK).

<4> Execute the EI instruction (when vector interrupts are used).

Figure 22-9 shows the timing of the interrupt signal generated by the low-voltage detector. The numbers in this timing chart correspond to <1> to <3> above.

- When stopping operation

Either of the following procedures must be executed.

- When using 8-bit memory manipulation instruction:
  Write 00H to LVIM.

- When using 1-bit memory manipulation instruction:
  Clear LVION to 0.

Cautions 1. Even when the LVI default start function is used, if it is set to LVI operation prohibition by the software, it operates as follows:

- **Does not perform low-voltage detection during LVION = 0.**
- **If a reset is generated while LVION = 0, LVION will be re-set to 1 when the CPU starts after reset release. There is a period when low-voltage detection cannot be performed normally, however, when a reset occurs due to WDT and illegal instruction execution. This is due to the fact that while the pulse width detected by LVI must be 200 μs max., LVION = 1 is set upon reset occurrence, and the CPU starts operating without waiting for the LVI stabilization time.**

2. When the LVI default start function (bit 0 (LVIOFF) of 000C1H = 0) is used, the LVIRF flag may become 1 from the beginning due to the power-on waveform.
For details of RESF, see CHAPTER 20 RESET FUNCTION.

DC Characteristics (2/16)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} = EV_{DD0} = EV_{DD1} ≤ 5.5 V, 1.8 V ≤ AV_{REF0} ≤ V_{DD}, 1.8 V ≤ AV_{REF1} ≤ V_{DD}, V_{SS} = EV_{SS0} = EV_{SS1} = AV_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low[Note 1]	I_{OL1}	Per pin for P00 to P02, P05, P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P120, P130, P131, P140, P141, P144, P145	4.0 V ≤ V_{DD} ≤ 5.5 V			8.5	mA
			2.7 V ≤ V_{DD} < 4.0 V			1.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			0.5	mA
		Per pin for P03, P04, P142, P143	4.0 V ≤ V_{DD} ≤ 5.5 V			8.5	mA
			2.7 V ≤ V_{DD} < 4.0 V			1.5	mA
			1.8 V ≤ V_{DD} < 2.7 V			0.6	mA
		Per pin for P60 to P63	4.0 V ≤ V_{DD} ≤ 5.5 V			15.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			3.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			2.0	mA
		Total of P00 to P04, P40 to P47, P120, P130, P131, P140 to P145 (When duty = 70%[Note 2])	4.0 V ≤ V_{DD} ≤ 5.5 V			20.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			15.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			9.0	mA
		Total of P05, P06, P10 to P17, P30, P31, P50 to P57, P60 to P67, P70 to P77, P80 to P87 (When duty = 70%[Note 2])	4.0 V ≤ V_{DD} ≤ 5.5 V			45.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			35.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			20.0	mA
		Total of all pins (When duty = 60%[Note 2])	4.0 V ≤ V_{DD} ≤ 5.5 V			65.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			50.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			29.0	mA
	I_{OL2}	Per pin for P20 to P27, P150 to P157	AV_{REF0} ≤ V_{DD}			0.4	mA
		Per pin for P110, P111	AV_{REF1} ≤ V_{DD}			0.4	mA

Notes 1. Value of current at which the device operation is guaranteed even if the current flows from an output pin to EV_{SS0}, EV_{SS1}, V_{SS}, and AV_{SS} pin.

2. Specification under conditions where the duty factor is 60% or 70%.

The output current value that has changed the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = (I_{OL} × 0.7)/(n × 0.01)

<Example> Where n = 50% and I_{OL} = 20.0 mA

Total output current of pins = (20.0 × 0.7)/(50 × 0.01) = 28.0 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

(3) Serial interface: Serial array unit (5/18)

(d) During communication at same potential (simplified I^2C mode)

- **Conventional-specification products (μPD78F116x)**

(T_A = –40 to +85°C, 2.7 V ≤ V_{DD} = EV_{DD0} = EV_{DD1} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = AV_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
<R> SCLr clock frequency	f_{SCL}	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ		400 Note	kHz
Hold time when SCLr = "L"	t_{LOW}	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	995		ns
Hold time when SCLr = "H"	t_{HIGH}	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	995		ns
Data setup time (reception)	$t_{SU:DAT}$	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	1/f_{MCK} + 120		ns
Data hold time (transmission)	$t_{HD:DAT}$	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	0	160	ns

<R> **Note** The value must also be f_{MCK}/4 or less.

- **Expanded-specification products (μPD78F116xA)**

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} = EV_{DD0} = EV_{DD1} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = AV_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
<R> SCLr clock frequency	f_{SCL}	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ		400 Note	kHz
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ		300 Note	kHz
Hold time when SCLr = "L"	t_{LOW}	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	995		ns
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ	1500		ns
Hold time when SCLr = "H"	t_{HIGH}	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	995		ns
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ	1500		ns
Data setup time (reception)	$t_{SU:DAT}$	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	1/f_{MCK} + 120		ns
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ	1/f_{MCK} + 230		ns
Data hold time (transmission)	$t_{HD:DAT}$	2.7 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	0	160	ns
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ	0	210	ns

<R> **Note** The value must also be f_{MCK}/4 or less.

(Remarks are given on the next page.)

(3) X1 oscillation: Ceramic resonator (AMPH = 1, RMC = 00H, T_A = –40 to +85°C)

Manufacturer	Part Number	SMD/ Lead	Frequency (MHz)	Recommended Circuit Constants		Oscillation Voltage Range	
				C1 (pF)	C2 (pF)	MIN. (V)	MAX. (V)
Murata Manufacturing Co., Ltd.	CSTCE12M0G55-R0	SMD	12.0	Internal (33)	Internal (33)	1.8	5.5
	CSTCE16M0V53-R0	SMD	16.0	Internal (15)	Internal (15)	1.8	
	CSTLS16M0X51-B0	Lead		Internal (5)	Internal (5)	1.8	
	CSTCE20M0V53-R0	SMD	20.0	Internal (15)	Internal (15)	1.9	
	CSTCG20M0V53-R0	Small SMD		Internal (15)	Internal (15)	2.0	
	CSTLS20M0X51-B0	Lead		Internal (5)	Internal (5)	1.9	
TOKO, Inc.	DCRHYC(P)12.00A	Lead	12.0	Internal (22)	Internal (22)	1.8	5.5
	DCRHZ(P)16.00A-15	Lead	16.0	Internal (15)	Internal (15)		
	DCRHZ(P)20.00A-15	Lead	20.0	Internal (15)	Internal (15)	2.0	
	DECRHZ20.00	SMD		Internal (10)	Internal (10)	1.8	

Caution The oscillator constants shown above are reference values based on evaluation in a specific environment by the resonator manufacturer. If it is necessary to optimize the oscillator characteristics in the actual application, apply to the resonator manufacturer for evaluation on the implementation circuit.

<R> **When doing so, check the conditions for using the AMPH bit, RMC register, and whether to enter or exit the STOP mode.**

The oscillation voltage and oscillation frequency only indicate the oscillator characteristic. Use the 78K0R/KG3 so that the internal operation conditions are within the specifications of the DC and AC characteristics.

DC Characteristics (2/16)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} = EV_{DD0} = EV_{DD1} ≤ 5.5 V, 1.8 V ≤ AV_{REF0} ≤ V_{DD}, 1.8 V ≤ AV_{REF1} ≤ V_{DD}, V_{SS} = EV_{SS0} = EV_{SS1} = AV_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low[Note 1]	I_{OL1}	Per pin for P00 to P02, P05, P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P120, P130, P131, P140, P141, P144, P145	4.0 V ≤ V_{DD} ≤ 5.5 V			8.5	mA
			2.7 V ≤ V_{DD} < 4.0 V			1.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			0.5	mA
		Per pin for P03, P04, P142, P143	4.0 V ≤ V_{DD} ≤ 5.5 V			8.5	mA
			2.7 V ≤ V_{DD} < 4.0 V			1.5	mA
			1.8 V ≤ V_{DD} < 2.7 V			0.6	mA
		Per pin for P60 to P63	4.0 V ≤ V_{DD} ≤ 5.5 V			15.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			3.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			2.0	mA
		Total of P00 to P04, P40 to P47, P120, P130, P131, P140 to P145 (When duty = 70%[Note 2])	4.0 V ≤ V_{DD} ≤ 5.5 V			20.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			15.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			9.0	mA
		Total of P05, P06, P10 to P17, P30, P31, P50 to P57, P60 to P67, P70 to P77, P80 to P87 (When duty = 70%[Note 2])	4.0 V ≤ V_{DD} ≤ 5.5 V			45.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			35.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			20.0	mA
		Total of all pins (When duty = 60%[Note 2])	4.0 V ≤ V_{DD} ≤ 5.5 V			65.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			50.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			29.0	mA
	I_{OL2}	Per pin for P20 to P27, P150 to P157	AV_{REF0} ≤ V_{DD}			0.4	mA
		Per pin for P110, P111	AV_{REF1} ≤ V_{DD}			0.4	mA

Notes 1. Value of current at which the device operation is guaranteed even if the current flows from an output pin to EV_{SS0}, EV_{SS1}, V_{SS}, and AV_{SS} pin.

2. Specification under conditions where the duty factor is 60% or 70%.

The output current value that has changed the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = (I_{OL} × 0.7)/(n × 0.01)

<Example> Where n = 50% and I_{OL} = 20.0 mA

Total output current of pins = (20.0 × 0.7)/(50 × 0.01) = 28.0 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

Caution P02 to P04, P43, P45, P142 to P144 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

APPENDIX C REVISION HISTORY

C.1 Major Revisions in This Edition

(1/5)

Page	Description	Classification
Throughout		
–	Change of status of **(A) grade products of the expanded-specification products** from under development to mass production	(b)
CHAPTER 1 OUTLINE		
p.18	Change of **1.1 Differences Between Conventional-Specification Products (μPD78F116x) and Expanded-Specification Products (μPD78F116xA)**	(c)
CHAPTER 3 CPU ARCHITECTURE		
p.62	Change of **Table 3-2. Internal ROM Capacity**	(a)
pp.67 to 73	Change of **Figure 3-9** to **Figure 3-15 Correspondence Between Data Memory and Addressing**	(c)
p.75	Addition of **Caution** to **3.2.1 (3) Stack pointer (SP)**	(c)
CHAPTER 4 PORT FUNCTIONS		
p.139	Change of **Figure 4-30. Block Diagram of P110 and P111**	(c)
CHAPTER 5 EXTERNAL BUS INTERFACE		
p.175	Addition of **5.6 Number of Instructed Wait Cycles According to External Wait Cycles**	(c)
CHAPTER 6 CLOCK GENERATOR		
pp.189, 190	Addition of f_{MAINC} to **Figure 6-1. Block Diagram of Clock Generator** and **Remark**	(c)
p.191	Change of description of AMPH bit in **Figure 6-2. Format of Clock Operation Mode Control Register (CMC)**	(c)
p.199	Change of description of RTCEN bit in **Figure 6-7. Format of Peripheral Enable Register (1/2)**	(c)
p.201	Change of **Caution 5** in **Figure 6-8. Format of Operation Speed Mode Control Register (OSMC)** and addition of **Caution 4**	(c)
p.221	Change of description of AMPH bit in **Table 6-4. CPU Clock Transition and SFR Register Setting Examples (1/4) (2)** and addition of **Remark**	(c)
p.222	Change of description of AMPH bit in **Table 6-4. CPU Clock Transition and SFR Register Setting Examples (2/4) (4)** and addition of **Remark**	(c)
p.224	Change of **(9) CPU clock changing from subsystem clock (D) to high-speed system clock (C)** in **Table 6-4. CPU Clock Transition and SFR Register Setting Examples (4/4)**	(c)
p.224	Change of **(11) • STOP mode (H) set while CPU is operating with internal high-speed oscillation clock (B) • STOP mode (I) set while CPU is operating with high-speed system clock (C)** in **Table 6-4. CPU Clock Transition and SFR Register Setting Examples (4/4)**	(c)
p.227	Change of **Table 6-6. Maximum Time Required for Main System Clock Switchover**	(c)
p.227	Change of **Table 6-8. Maximum Number of Clocks Required in Type 2**	(c)
p.228	Change of **Table 6-9. Maximum Number of Clocks Required in Type 3** and addition of **Remark**	(c)
CHAPTER 7 TIMER ARRAY UNIT		
p.232	Change of **Figure 7-1. Block Diagram of Timer Array Unit**	(c)
p.239	Change of description of CKS0n bit in **Figure 7-6. Format of Timer Mode Register 0n (TMR0n) (1/3)**	(a)

Remark "Classification" in the above table classifies revisions as follows.

(a): Error correction, (b): Addition/change of specifications, (c): Addition/change of description or note, (d): Addition/change of package, part number, or management division, (e): Addition/change of related documents